

MICROBONDS ANNOUNCES CERTIFICATION OF X-WIRE™ TECHNOLOGY at TANAKA'S SAGA, JAPAN PRODUCTION FACILITIES

◇ *Tanaka certifies X-Wire™ Technology at its Saga Japan production facilities*

(TORONTO, Canada), (February 1, 2007) -Microbonds Inc., an inventor of insulation for bonding wires and related processes, today announced that it and Tanaka Denshi Kogyo K.K., the leading global supplier of gold bonding wire have certified the technology readiness of Tanaka to manufacture X-Wire™ from its Saga, Japan production facilities. Actual production quantities of Tanaka X-Wire™ are expected to be available in mid Q1, 2007.

“We are pleased to have met our objective of having Tanaka Denshi be production capable for X-Wire™ production from its Saga, Japan facilities as scheduled. Our long-term relationship with Tanaka allows customers a unique and compelling solution to many interconnect challenges. We look forward to production shipments of X-Wire™ with a partner known for its long term commitment to quality, technical leadership and market responsibility” said John Scott, CEO of Microbonds, Inc..

About X-Wire Technology

Microbonds' X-Wire™ Technology is an interconnect solution which consists of a proprietary insulation applied to bare bonding wires. Insulated bonding wires have been added to the 2006 ITRS Roadmap. See <http://www.itrs.net/Links/2006Update/2006UpdateFinal.htm>. Microbonds licenses X-Wire Technology to global bond wire manufacturers.

X-Wire™ Technology enables interconnect bonding wires to touch and cross without causing an electrical short. With X-Wire™, customers can solve yield losses due to wire sweep, increase I/O counts, design new package types, achieve new geometries through new bonding rules, as well as reduce costs through direct to ball bonding and thinner diameter wires.

About Tanaka

Tanaka Kikinzoku is a global provider of precious metal materials, such as bonding wires and targets that support the production of semiconductor devices from wafer to assembly processing. Based in Tokyo, Japan, the company has been in business for over 100 years. Its products play a vital role in the industrial fields, such as energy conservation, environmental control, health care, electric and electronics, automobile, telecommunication and semiconductors. For more information, please visit: www.tanaka-precious.com

About Microbonds

Microbonds, Inc. is a pioneer in the development of unique microchip-interconnect solutions for use in the design and assembly of microelectronic devices. The company's X-Wire Technology enables the development of advanced microchip packages while improving manufacturing reliability by reducing yield losses due to interconnect shorting..

For more information, see www.microbonds.com

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